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**Wu et al.**

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(54) **MEMS PACKAGE STRUCTURE AND MANUFACTURING METHOD THEREOF**

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CPC ..... **B81B 7/0058** (2013.01); **B81B 7/0041** (2013.01); **B81C 1/00269** (2013.01); **G02B 27/0006** (2013.01); **B81B 2201/042** (2013.01); **B81C 2203/019** (2013.01); **G02B 26/0833** (2013.01)

(58) **Field of Classification Search**

None  
See application file for complete search history.

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(57) **ABSTRACT**

A MEMS package structure includes a base, a MEMS device, a first cover, a second cover and a glass frit. The base includes a recess. The MEMS device is disposed in the recess. The first cover is disposed in the recess and covering the MEMS device. The second cover is disposed on the base and covering the recess. The glass frit is disposed between the base and the second cover. A MEMS package structure includes the base, the MEMS device, the first cover, a second cover, a first metal frame and a first sealing medium. The first metal frame is disposed around the second cover, and the second cover and the first metal frame collectively are disposed on the base and covering the recess. The first sealing medium is disposed between the first metal frame and the base. Manufacturing methods of the MEMS package structures above are further provided.

**2 Claims, 7 Drawing Sheets**

